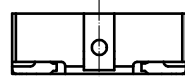
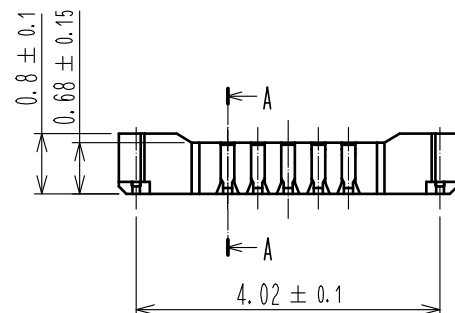
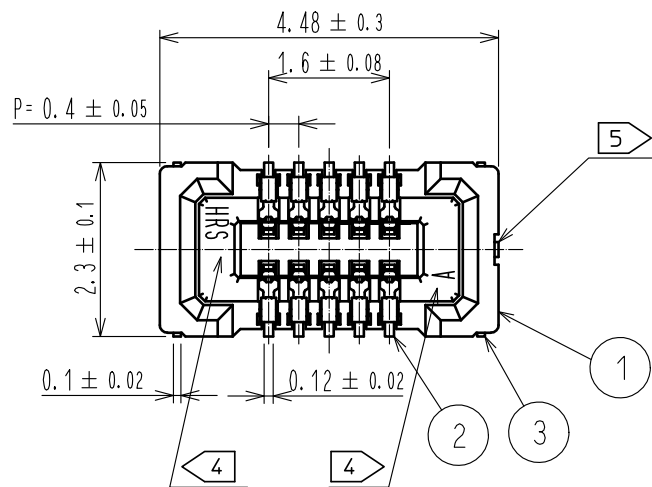
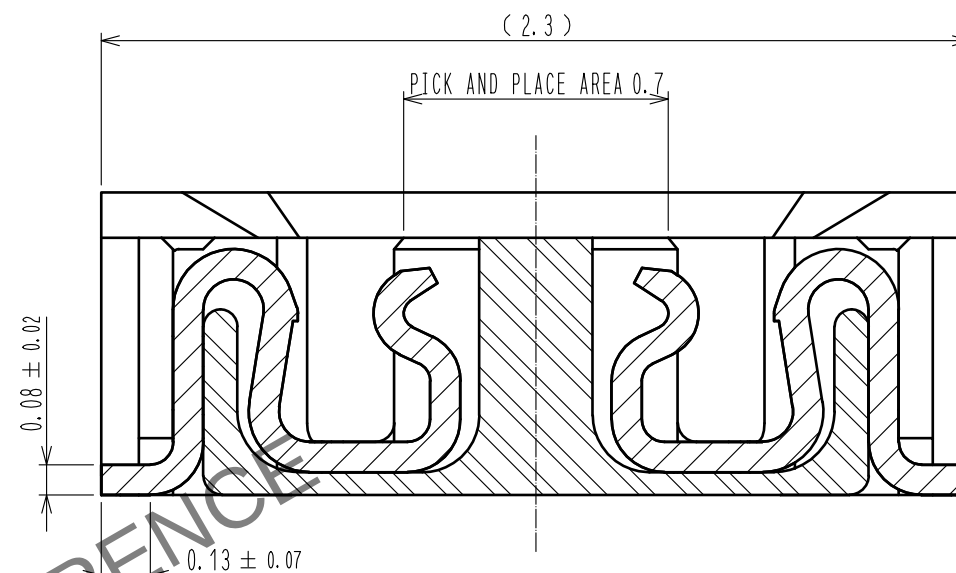


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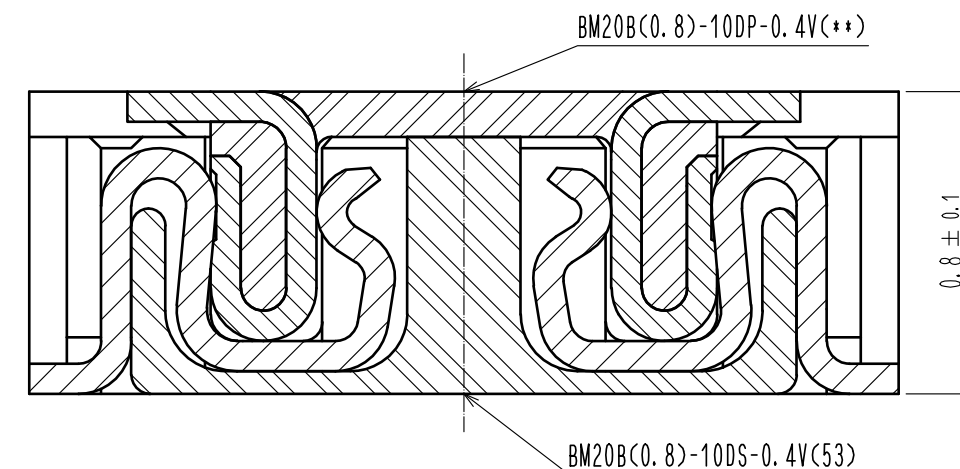


- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05μm MIN
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
3 MATAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
5 GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

A-A(50:1)



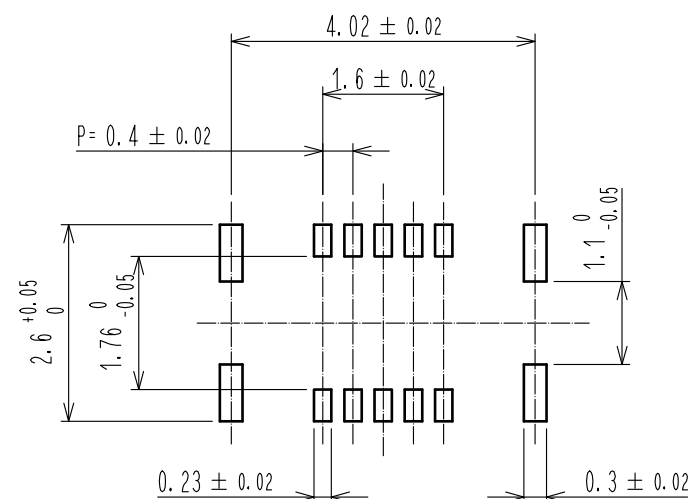
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	BRASS	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	15.10.17	DRAWING NO.	EDC-332314-53-01
		CHECKED : TS. MIYAZAKI	15.10.17	PART NO.	BM20B(0.8)-10DS-0.4V(53)
		DESIGNED : RT. SHIMIZU	15.10.16	CODE NO.	CL684-9008-4-53
		DRAWN : KR. AJITO	15.10.16		
					1/3

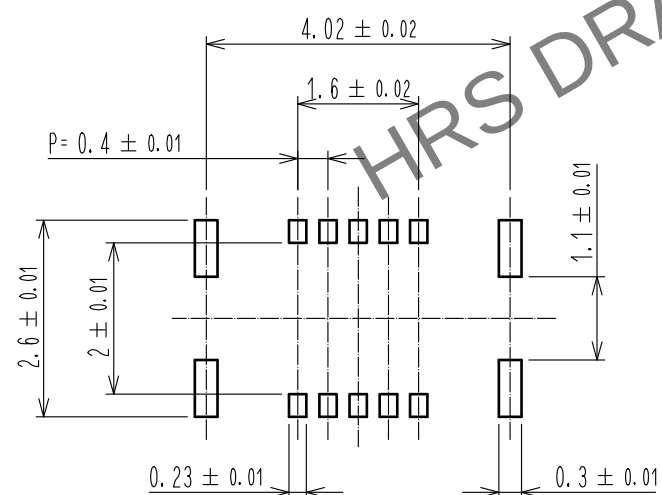
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◆RECOMMENDED PCB LAYOUT

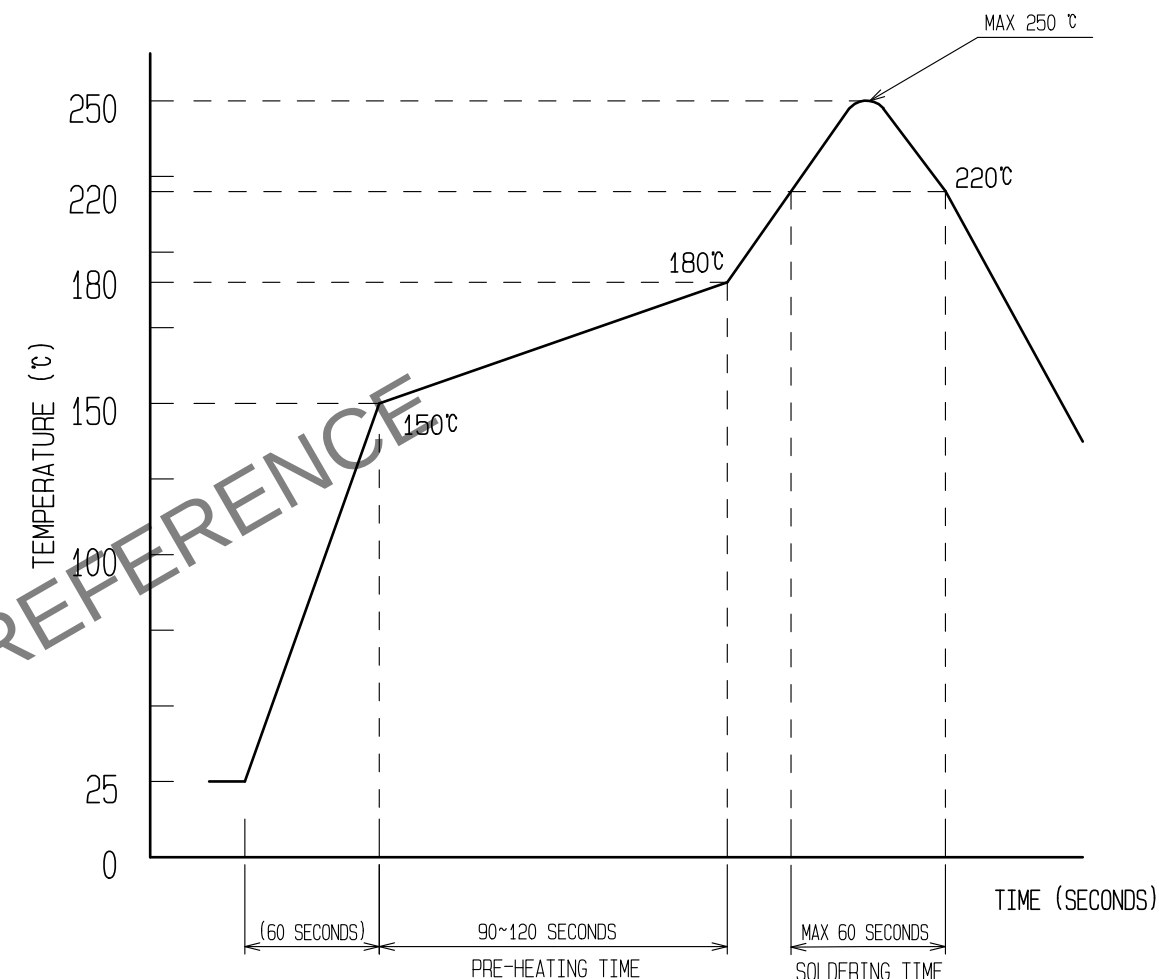


◆RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

6 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC-332314-53-01
PART NO.	BM20B(0.8)-10DS-0.4V(53)
CODE NO.	CL684-9008-4-53

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